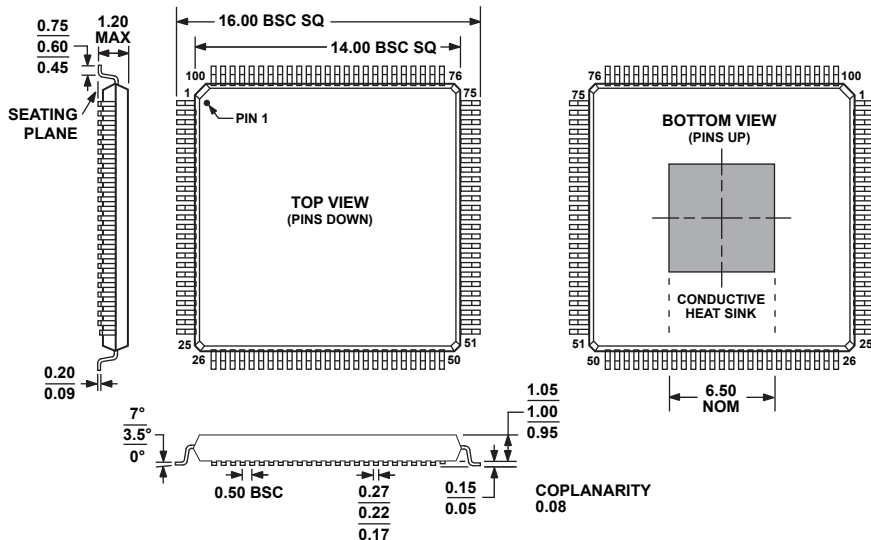


100-Lead Thin Quad Flat Package, Exposed Pad [TQFP_EP]

(SV-100-1)

Dimensions shown in millimeters



COMPLIANT TO JEDEC STANDARDS MS-026-AED-HD

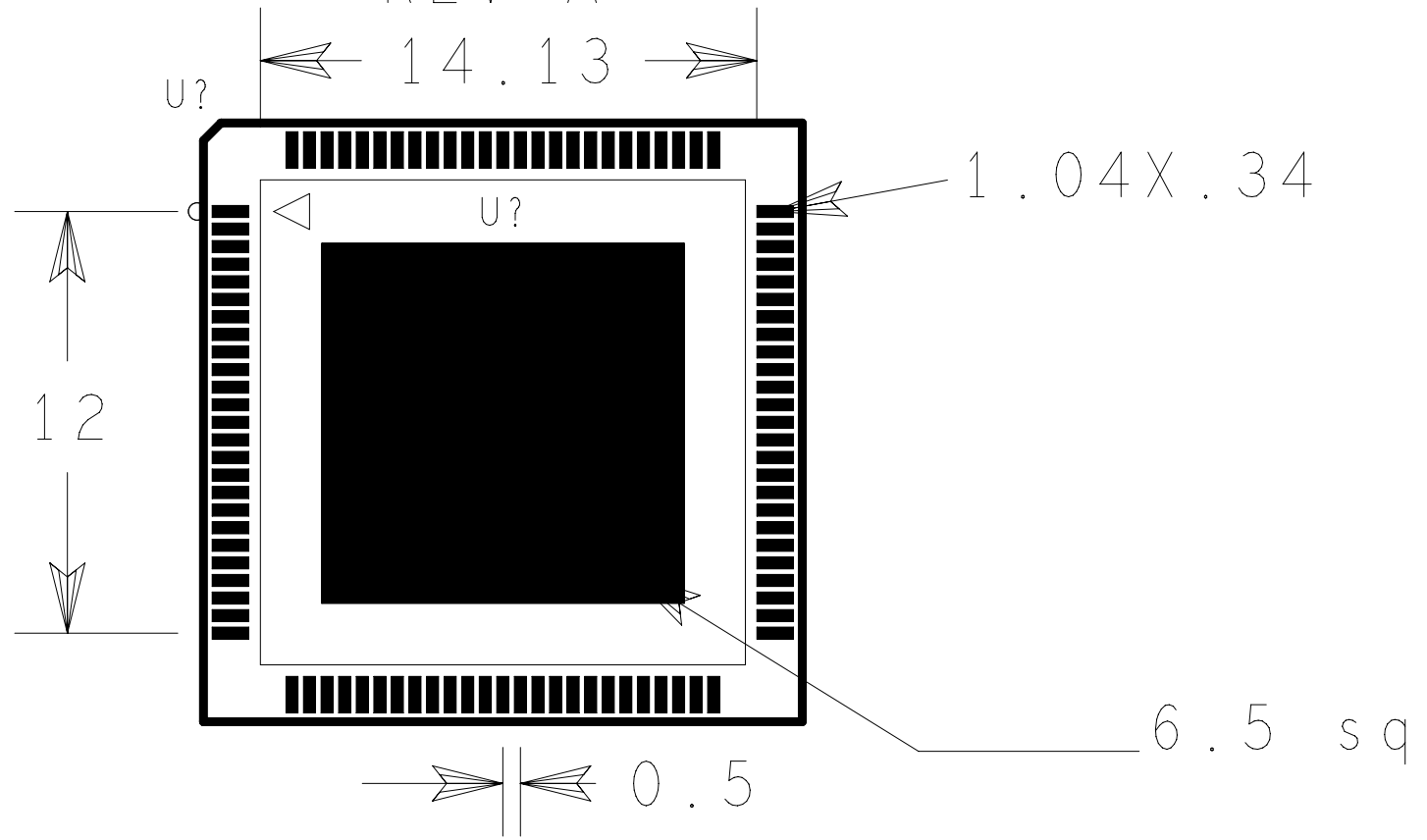
NOTES

1. CENTER FIGURES ARE TYPICAL UNLESS OTHERWISE NOTED.
2. THE PACKAGE HAS A CONDUCTIVE HEAT SLUG TO HELP DISSIPATE HEAT AND ENSURE RELIABLE OPERATION OF THE DEVICE OVER THE FULL INDUSTRIAL TEMPERATURE RANGE. THE SLUG IS EXPOSED ON THE BOTTOM OF THE PACKAGE AND ELECTRICALLY CONNECTED TO CHIP GROUND. IT IS RECOMMENDED THAT NO PCB SIGNAL TRACES OR VIAS BE LOCATED UNDER THE PACKAGE THAT COULD COME IN CONTACT WITH THE CONDUCTIVE SLUG. ATTACHING THE SLUG TO A GROUND PLANE WILL REDUCE THE JUNCTION TEMPERATURE OF THE DEVICE WHICH MAY BE BENEFICIAL IN HIGH TEMPERATURE ENVIRONMENTS.

Analog Devices

SV-100-1

REV A



(DIM. are in MM)

LAST MODIFIED 5/25/07